

The logo for DIGITIMES, featuring the word "DIGITIMES" in a bold, white, sans-serif font. The letter "D" is stylized with a white outline and a small white square at its top-left corner. The text is set against a solid orange rectangular background.

(Taiwan)

Heterogeneous integration technology continues to evolve EVG talks about hybrid bonding and NIL trends – September 10, 2023

异质整合技术不断演进 EVG谈混合键合、NIL趋势

- 康琼之／台北
- 2023-09-11

人工智能（AI）带动服务器、高端芯片及先进封装需求，作为次时代先进封装技术的3D芯片也成为潜力之星，混合键合（hybrid bonding）技术扮演关键角色，晶圆代工三大龙头台积电、三星电子（Samsung Electronics）、英特尔（Intel）也都看好其未来...

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